

Q2119A Automatic Wire Bonder

Designed for Complex Hybrid, Opto-Electronic and I.C. Assembly Requirements

Current Specifications*

Standard Features – Hardware

4" x 4" Bond Area
4 Channel Ultrasonic Generator (60 KHz)
Brushless Motors with Smart Feedback
Solid State Vision System
Matrox Pattern Recognition System
Flat Panel Monitor
Wireless Mouse
Stereo Zoom 4 Microscope
Galil Motion Control System
Windows XP™ OS
Digital Temperature Controller
Fiber Optic Light Source

Standard Features – Software

Point and Click Bond Targeting
Simple, Intuitive Programming
Easy Bond Process Editing
Extensive Program Storage
Bond Parameter Library
Unlimited Wire Program Storage
Program Wire Groups for Multi Device,
High Wire Count Hybrids
Custom Wire Profiles Available for
Unique Applications
Ball Bumping and Coining
Security Bond

Specifications

Gold Wire

Size Range
0.0007" – 0.003" (17.8 – 76.2 microns)
Maximum Wires Per Device
Unlimited

Bonding Speed/Wire

400–550 ms

± 0.0000625" (± 1.6 microns)
Bonding Pitch
0.00275" (69.9 microns)

Options and Accessories

Options

Programmable Temperature Controller(s)
Programmable U/S Generator
High Frequency USG / Transducer
Large Table Travel (Up to 12" x 12")

Accessories

Heated Adjustable Workholder
Ethernet Adapter for Networking Bonders
Additional Fiber Optic Light Source

Miscellaneous

Remote Diagnostics Capability
CE Mark

Facilities

Electric 120 VAC, 50/60 Hz, 20A
N2 or clean, dry air
Vacuum / Air as required for workholder

Dimension/Weight

Height: 72" (182.88 cm)
Width: 39" (99.09 cm)
Depth: 37" (93.98 cm)
Table Height: 40" (101.60 cm)
Weight: 600 pounds (273 Kg)
Crated Weight: 750 pounds (341 Kg)

* Subject to Change

010109

XY Table

Resolution

1258F Quarry Lane
925-461-0100

Pleasanton CA 94566
www.questarinc.com